

## **IN THE CLAIMS:**

### **Amendments to the Claims**

Please amend claims 5, 6, 12, 13, 15 and 16 as shown below.

### **Listing of Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (canceled)

2. (previously presented) The pattern inspection method according to Claim 5, further comprising the step of displaying the outputted image of the extracted defect candidate on a display screen.

3. (previously presented) The pattern inspection method according to Claim 5, wherein said information outputted at the outputting step includes data enabling the classification of the defect.

Claim 4 (canceled)

5. (currently amended) A pattern inspection method , comprising the steps of:

irradiating either a charged particle or a light on a surface of a substrate on which a pattern is formed;

producing an image of said substrate surface by detecting any of a reflected light, secondary electron, reflected electron, transmitted electron, or absorbed electron generated from said substrate as a result of the irradiation;

producing a digital image by subjecting the produced image signal to A/D conversion;

comparing the digital image against a reference image and extracting a defect candidate;

outputting an image of the extracted defect candidate and data comprising the location of this defect candidate, via either a storage medium or a network;

displaying in a map format the defect candidate location data outputted via either said storage medium or network; and

designating said defect candidate location data displayed in a map format on said displayed map, and thereby simultaneously displaying an image of a defect candidate corresponding to ~~this~~ the designated location on the screen.

6. (currently amended) A pattern inspection method, comprising the steps of:

detecting a defect candidate of a pattern by using an inspecting means;

outputting an image of this detected defect candidate and data including location information of the defect candidate;

inputting said outputted defect candidate image and data including location information of the defect candidate to processing means;

displaying the inputted defect candidate data on a screen in map format; and

simultaneously displaying on the screen an image of ~~the~~ a defect candidate which is designated on the map displayed on the screen.

Claims 7-9 (canceled)

10. (original) The pattern inspection method according to Claim 6, further comprising the step of changing threshold value data on said screen, when detecting a defect candidate of said pattern using said inspecting means.

11. (original) The pattern inspection method according to Claim 10, wherein defect candidate location data displayed in map format is updated and displayed in accordance with said changed threshold value data.

12. (currently amended) The pattern inspection method according to Claim 6, wherein, in said step for displaying on the screen, said defect candidates are classified using the images of defect candidates outputted via either said storage medium or network and data comprising the locations of ~~these~~the defect candidates, and location data of ~~these~~the classified defect candidates is identified by classification and displayed in map format on said screen.

13. (currently amended) The pattern inspection method according to Claim 6, wherein, in said step for displaying on the screen, said defect candidates are classified using the images of defect candidates outputted via either said storage medium or network and data comprising the locations of ~~these~~the defect candidates, and location data of the designated defect candidate from among these classified defect candidates is displayed in map format on said screen.

14. (original) The pattern inspection method according to Claim 13, wherein location data of defect candidates of a plurality of classifications designated from among said classified defect candidates is identified by said classifications and displayed in map format on said screen.

15. (currently amended) The pattern inspection method according to Claim 13, further comprising the steps of processing said inputted image of said defect candidate and data comprising the location of this defect candidate by said processing means, and thereafter outputting ~~{same}~~ via said network.

16. (currently amended) A pattern inspection method, comprising the steps of:

imaging a substrate on which a pattern is formed; processing an image obtained by said imaging to detect a defect candidate of said pattern;

outputting an image of said detected defect candidate and data including location information of the defect candidate while carrying out the step of imaging said substrate and the step of detecting a defect candidate of said pattern; and

simultaneously displaying, on a screen, said defect candidate image and data including the location information of the defect candidate outputted via this network;

wherein, in the step of displaying, said defect candidate data is displayed in a map format on said screen and ~~the image~~ said defect candidate image which is simultaneously displayed on said screen is designated on said map displayed on said screen.

Claims 17-19 (canceled)

20. (original) The pattern inspection method according to Claim 16, further comprising the step of changing threshold value data for detecting a defect candidate of said pattern on said screen.

21. (previously presented) The pattern inspection method according to Claim 20, wherein the location of the defect candidate displayed in map format is updated and displayed in accordance with said changed threshold value data.

22. (original) The pattern inspection method according to Claim 16, wherein, in the step for displaying on said screen, said defect candidates are classified using the images of defect candidates and data including location information of the defect candidates outputted via either said storage medium or network, and identically classified defect candidates are displayed in map format on said screen.

23. (original) The pattern inspection method according to Claim 16, wherein, in the step of displaying on said screen, said defect candidates are classified using the images of defect candidates and data including location information of the defect candidates outputted via either said storage medium or network, and defect candidate location data designated from among the classified defect candidates is displayed in map format on said screen.

24. (original) The pattern inspection method according to Claim 23, wherein plural classes of defect candidates designated from among said classified defect candidates are displayed on said screen discriminately from each other in the map format.